

CLAIMS

1. A development apparatus for manufacturing a semiconductor device, said development apparatus discharging a developer onto a surface of a semiconductor substrate and comprising:

5 a nozzle pipe for supplying said developer; and  
a nozzle having a shape of a spoon with a taper  
and discharging said developer supplied by said nozzle pipe  
10 onto said surface of said substrate, wherein said nozzle  
sprays said developer onto said surface of said substrate  
at any spray angle under a low and constant pressure.

2. A development apparatus for manufacturing a semiconductor device, said development apparatus discharging a developer onto a surface of a semiconductor substrate and comprising:

15 a nozzle pipe for supplying said developer;  
a nozzle having a shape of a spoon with a taper  
and discharging said developer supplied by said nozzle pipe  
20 onto said surface of said substrate; and  
a scanning device for simultaneously scanning  
said nozzle pipe and said nozzle above said substrate in a  
stationary state, wherein said nozzle sprays said developer  
onto said surface of said substrate at any spray angle  
25 under a low and constant pressure.

3. The development apparatus according to claim 2, which further comprises an adjusting device for  
adjusting a position of said nozzle with respect to a  
position of said nozzle pipe.

30 4. The development apparatus according to claim 3, wherein said adjusting device moves said nozzle with  
respect to said nozzle pipe.

5. The development apparatus according to claim 3, wherein said adjusting device moves said nozzle pipe with respect to said nozzle.